MMBF170L, NVBF170L

MOSFET – N-Channel, SOT-23
500 mA, 60 V

Features

- NVBF Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free and are RoHS Compliant

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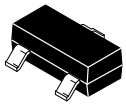
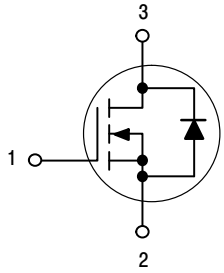
500 mA, 60 V
$R_{DS(on)}$ = 5 Ω



SOT−23
CASE 318
STYLE 21

N−Channel



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain−Source Voltage	V_{DSS}	60	Vdc
Drain−Gate Voltage	V_{DGS}	60	Vdc
Gate−Source Voltage – Continuous – Non−repetitive ($t_p \le 50$ μs)	 V_{GS} V_{GSM}	 ±20 ±40	 Vdc Vpk
Drain Current – Continuous – Pulsed	I_D I_{DM}	0.5 0.8	Adc

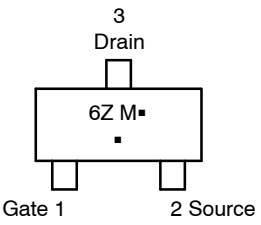
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board (Note 1.) T_A = 25°C Derate above 25°C	P_D	 225 1.8	 mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR−5 = 1.0 × 0.75 × 0.062 in.

MARKING DIAGRAM & PIN ASSIGNMENT



6Z = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Drain–Source Breakdown Voltage (V_{GS} = 0, I_D = 100 μA)	$V_{(BR)DSS}$	60	–	Vdc
Gate–Body Leakage Current, Forward (V_{GSF} = 15 Vdc, V_{DS} = 0)	I_{GSS}	–	10	nAdc
ON CHARACTERISTICS (Note 1)				
Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 1.0 mA)	$V_{GS(th)}$	0.8	3.0	Vdc
Static Drain–Source On–Resistance (V_{GS} = 10 Vdc, I_D = 200 mA)	$r_{DS(on)}$	–	5.0	Ω
On–State Drain Current (V_{DS} = 25 Vdc, V_{GS} = 0)	$I_{D(off)}$	–	0.5	μA
DYNAMIC CHARACTERISTICS				
Input Capacitance (V_{DS} = 10 Vdc, V_{GS} = 0 V, f = 1.0 MHz)	C_{iss}	–	60	pF
SWITCHING CHARACTERISTICS (Note 1)				
Turn–On Delay Time	(V_{DD} = 25 Vdc, I_D = 500 mA, R_{gen} = 50 Ω) Figure 1	$t_{d(on)}$	–	10	ns
Turn–Off Delay Time		$t_{d(off)}$	–	10	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

ORDERING INFORMATION

Device	Package	Shipping†
MMBF170LT1G	SOT–23 (TO–236) (Pb–Free)	3000 / Tape & Reel
MMBF170LT3G	SOT–23 (TO–236) (Pb–Free)	10000 / Tape & Reel
NVBF170LT1G*	SOT–23 (TO–236) (Pb–Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

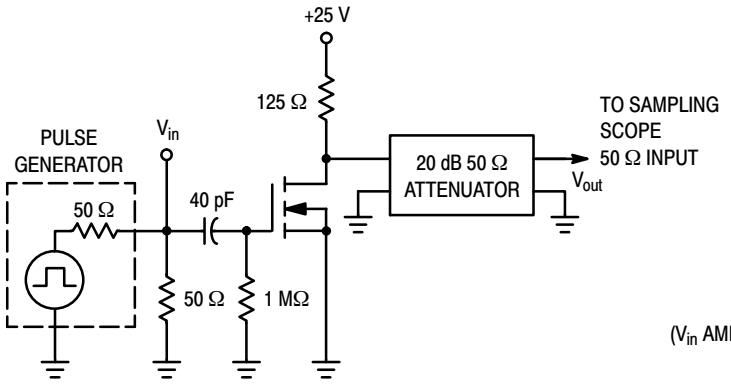


Figure 1. Switching Test Circuit

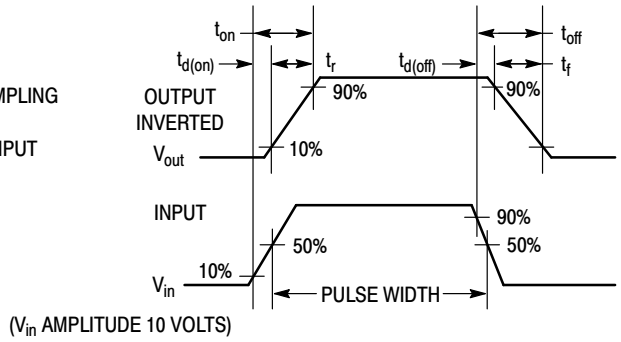


Figure 2. Switching Waveform

TYPICAL ELECTRICAL CHARACTERISTICS

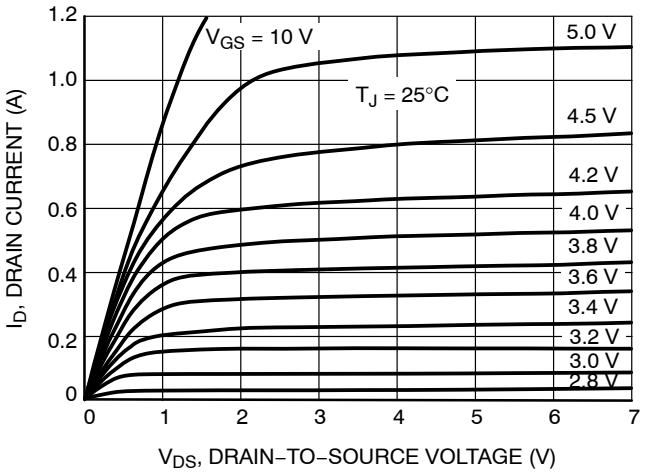


Figure 3. On−Region Characteristics

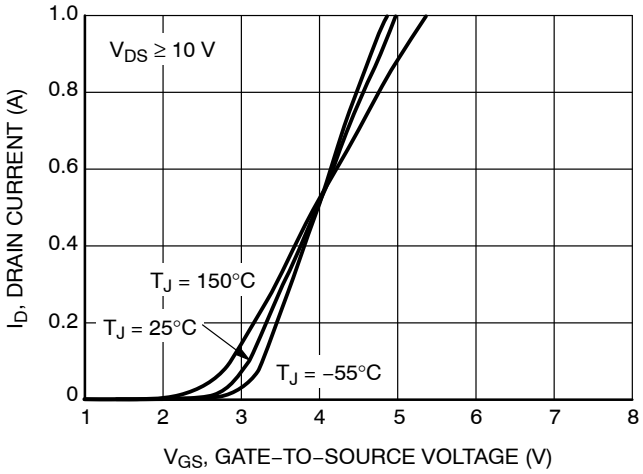


Figure 4. Transfer Characteristics

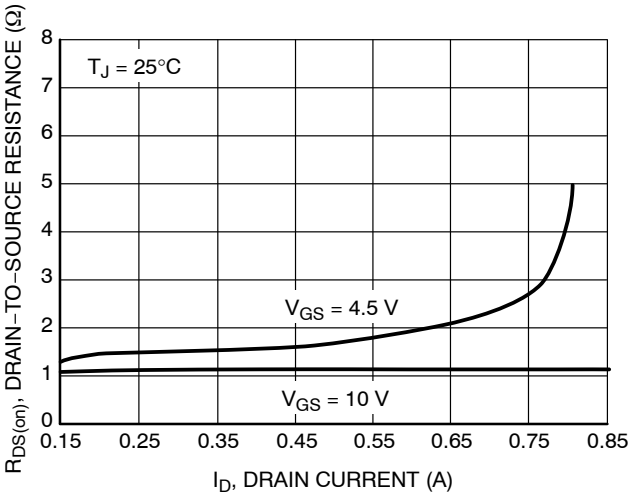


Figure 5. On−Resistance vs. Drain Current and Gate Voltage

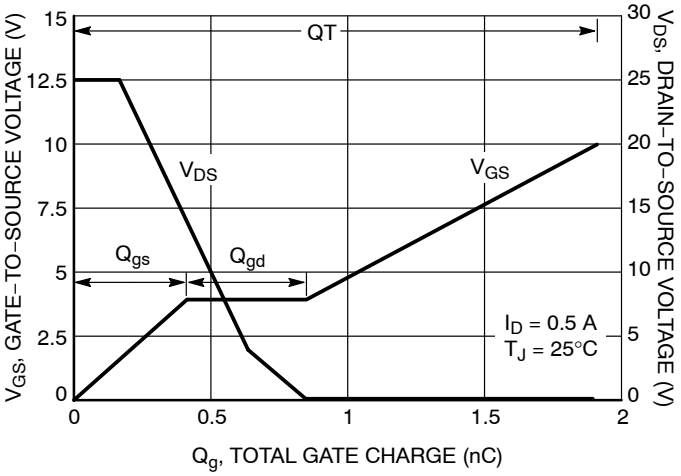


Figure 6. Gate−to−Source and Drain−to−Source Voltage vs. Total Charge

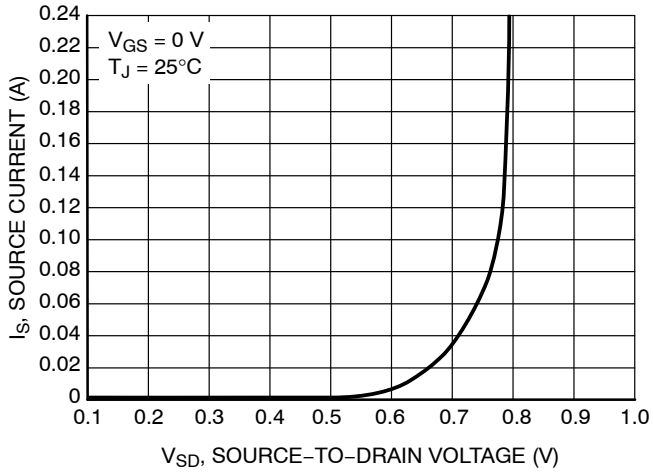


Figure 7. Diode Forward Voltage vs. Current

TYPICAL ELECTRICAL CHARACTERISTICS

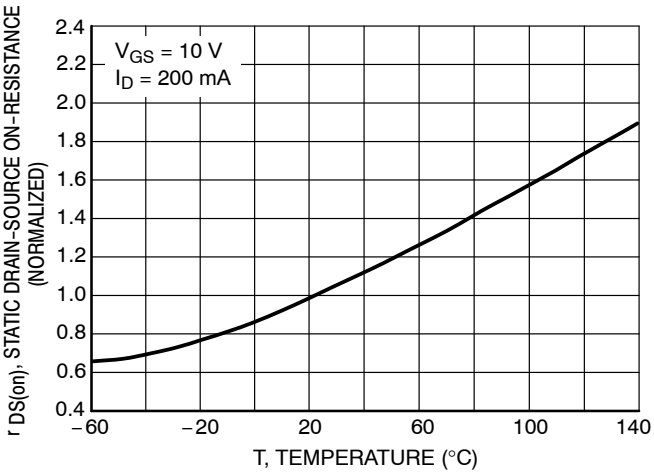


Figure 8. Temperature versus Static Drain−Source On−Resistance

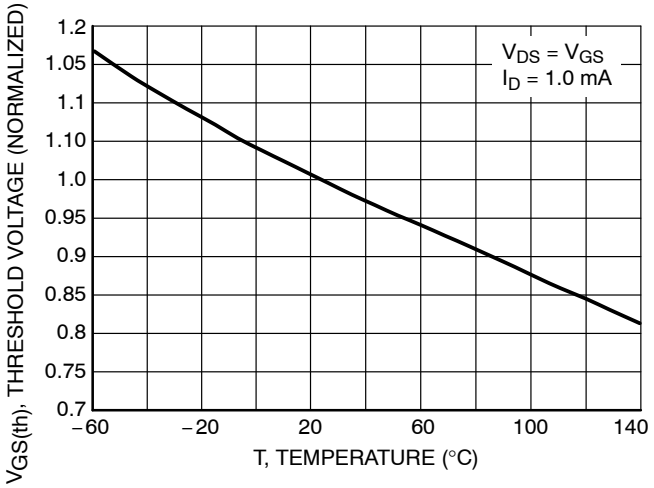
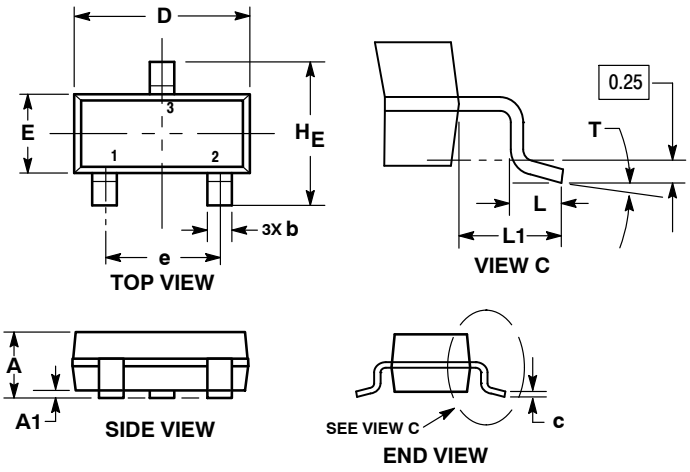


Figure 9. Temperature versus Gate Threshold Voltage

PACKAGE DIMENSIONS

SOT−23 (TO−236)
CASE 318−08
ISSUE AR

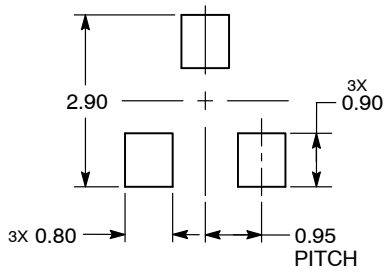


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
H_E	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	−−−	10 °	0 °	−−−	10 °

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5817−1050

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative